

# Model : MBA24005 Series

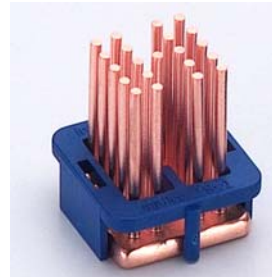
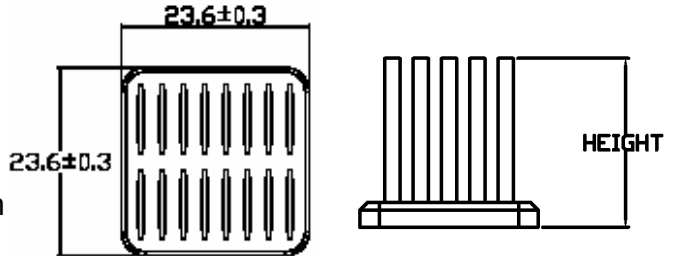


## BGA Heat Sink Specification

For 24x24 Chip set

1. Material : CU1100
2. Dimension :  
 Foot print : 24x24mm  
 Height : 12,15,18,21,23,28,33 mm  
 Base (thickness) : 2.6mm

3. Finish: Antioxidant Treatment
4. Chip set package thickness and clip color  
 3.3+/-0.25mm - Yellow clip  
 1.7+/-0.25mm - Blue clip  
 0.8+/-0.25mm - Orange clip
5. Accessory :  
 Clip : Plastic (UL94-V0)  
 Thermal pad : T710 or others



## Performance

Heat Source (LxW)	15x15
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